

"TECH" pool - high tech pooling from Eurocircuits

"TECH pool" – Higher technology order-pooling

As components get smaller designers have to use ever finer tracks, gaps and via holes. Increasingly our customers are finding that they require designs outside the specifications of our "STANDARD pool" service. To meet this need we have created a new higher specification pooling service, "TECH pool". This offers 100µm technology with all the benefits of an order-pooling service. With the launch of our "TECH pool" service Eurocircuits offers the largest PCB technology spectrum of any online pooling service in Europe.

What do you get?

- A one page menu for fast ordering of rigid fine-line PCBs
- Up to 8 layers, from 1 piece onwards
- 100µm 4mil technology boards at pooling prices
- Fully-finished with 2 solder-masks and 1 silk-screen
- Lead-free finish: electroless nickel immersion gold (ENIG or Che Ni/Au)
- FR-4 RoHS compliant material optimised for lead-free soldering with standard build-up
- No tooling charges
- No minimum order charge
- 100% manufacturability check prior to production
- Direct online price-calculation and ordering

How to get prices and place orders?

Log in and go to <u>Place order</u>. Enter number of layers, dimensions and delivery term and that's it nothing more. You see the price at once. Attach files and the order is placed. To choose options open the technical specifications and select what you need.

New user?

Not yet signed up to **Eurocircuits** and our other low-cost online services? Just go to <u>Sign up</u> and fill in the short form.

How do we keep "TECH pool" prices down?

Eurocircuits are specialist manufacturers of prototype and small batch PCBs. We are experts in orderpooling. Placing different orders on a standard production pooling panel minimizes set-up and production costs so you get good prices and no tooling charges. Because of the large numbers of orders we receive daily, we can offer a large number of technological options in our pooling services. We do a 100% check on your data before manufacture to make sure that you get the boards you want.

Number of layers2, 4, 6, 8Maximum PCB dimension410mm x 410mmMinimum PCB dimension5mm x 5mmBase materialFR-4, Td>=325°C, T260>=60', T288>=5', CTEz=<3.7%, Tg>=150°CBase material thickness1.55mmBase copper foil - outer layers12µml/%ozBase copper foil - inner layers12µml/%ozSurface finishENIGSoldermask type/colourLPI: GreenExtra optionsPeelable mask, via fillingLegend colourWhite one or both sidesMin. track width/spacing0.100mmMin. finished hole size0.15mm. Press fit holesMinimum outer layer pad diameter = finished hole size + listed valueHole ≤ 0.45: 0.300mmMinimum copper to board-edge clearance - outer layers0.250mm (routed), 0.450mm (V-cut). Copper up to edge. Plated holes on edgeMinimum copper to board-edge - inner layers0.400mm (routed), 0.450mm (V-cut). Copper up to edge. Plated holes on edgeSlots and cut-outs0.5, 0.8, 1.0, 1.2, 1.6, >= 2.0mm toolDelivery panels2.0mm break-routed + V-cutMultilayer-buildStandardLumarkingAvailableStencil material130µm stainless steelMaximum stencil size600 x 600mm		
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Stencil material 130µm stainless steel	Electrical test	Standard
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	Maximum stencil size	600 x 600mm